

10/675,698

PATENT

AMENDMENT A (PRELIMINARY)

SPECIFICATION AMENDMENTS

At paragraph 14, please amend the text as follows:

[0014] Figures ~~2A, 2B and 2C~~ 2A, 2B, 2C and 2D together are a circuit schematic diagram of an RF module with an LTCC substrate in accordance with one embodiment of the presently claimed invention.

At paragraph 15, please amend the text as follows:

[0015] Figure 3 is a circuit schematic diagram of a multiple pole bandpass filter used in the circuit of Figures ~~2A, 2B and 2C~~ 2A, 2B, 2C and 2D.

At paragraph 16, please amend the text as follows:

[0016] Figures 4A-4H illustrate the eight conductive electrode patterns of the seven layers of an LTCC substrate used to implement the circuit of Figures ~~2A-2C~~ 2A-2D.

At paragraph 22, please amend the text as follows:

[0022] Referring to Figures ~~2A-2C~~ 2A-2D together, an RF circuit module with an LTCC substrate in accordance with one embodiment of the presently claimed invention includes two surface-mounted IC chips, IC1, IC2 and a number of various surface-mounted or buried passive support components, i.e., resistors, capacitors and inductors, interconnected substantially as shown, and interfaced with external circuitry by way of an array IO1 of input/output connections. The specific functions and operations performed by the integrated circuits IC1, IC2 will not be described as they are not material to the subject invention. Selected ones of the outlying passive components which are material to the subject invention are discussed in more detail below.

At paragraph 28, please amend the text as follows:

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AMENDMENT A (PRELIMINARY)

[0028] Referring to Figures 4A-4H, the seven layers of ceramic material forming the LTCC substrate for the circuit of Figures ~~2A-2C~~ 2A-2D use various electrode patterns to form the bandpass filter F1, balun B1 and bypass capacitors C101-C108. As indicated in Figures 4A-4H, the eight electrode patterns are identified as conductor 7, 6, 5, 4, 3, 2, 1 and 0, respectively. Accordingly, Figures 4A, 4B, 4C, 4D, 4E, 4F, 4G and 4H correspond to electrode patterns 7, 6, 5, 4, 3, 2, 1 and 0, respectively, with electrode patterns 1 and 0 being on the top and bottom, respectively, of the first layer of ceramic material.